



Items	Description
Model	NXP-450
Min.PCB size	L 120mm * W 60mm
Max.PCB size	L 550mm * W 450mm
PCB top side / bottom side clearance	Max.Upper 100mm/ bottom 50mm
PCB process edge	4mm
Boards handling system	
Conveyor system	3 independent zone with independent control, chain and special turn plate
Conveyor heights	850+/-50mm
Width adjustment	60mm to 460mm
Width adjustment accuracy	+/-0.2mm
Conveyor direction	Left to right / right to left
Preheating system – Bottom side	
Preheating temperature/ Power	Max.160° C (PCB surface)/ Max.18KW
Temperature control accuracy	+/-2° C@3 sigma/Cpk≥1.33
Heater	Phillips Cesium light, independent control
Heating area	L 650MM * W 580MM
Preheating system – Top side	
Preheating temperature/ power	Max. 160° C (PCB surface)/ Max.8KW
Temperature control accuracy	+/-2° C@3 sigma/Cpk≥1.33
Heater	Hot air, independent control
Fluxing system	
Fluxer nozzle	micro drop jet fluxer
Fluxing wet area	Ø2 mm to Ø5mm
flux types	alcohol or water based
Fluxing Controller	automatic level control with capacitive sensor
Selective position method	X-Y Platform
Position speed/ accuracy	Max.400mm/s , +/-0.25mm
flux container	3L pressure tank
Soldering Unit for Soldering Processes	
solder pot compatible for lead free soldering	Standard
nitrogen operation	Standard
automatic wave height and solder level control	Standard
automatic wire solder feeder	Standard
wettable and non-wettable quick change nozzles	Standard
solder bath temperature	300° C
Temperature control accuracy	+/-2° C@3 sigma/Cpk≥1.33
Solder pot capacity	12kg lead free
Wave heights	Max.5mm
Solder pot moving speed	Max.400mm/s
Soldering nozzle dimensions	Ø5 to Ø12mm (or customized)
Control system	
Power supply	380VAC,3 P, 50/60Hz, 52A
PCB data import	GERB file, Offline file import, Image program
Programing interface	Windows interface
Power	35KW

NXP-series

In-line Selective soldering machine



NXP series selective soldering machine

Main features

- Lead free acceptable
- Through-hole soldering flexibility - single point, drag, mini-wave, or dip soldering
- Modular selective soldering system, consisting of a fluxer module, pre-heater module and Selective soldering pot module that can be fully configured as standard needed.
- High process reliability through automatic wave height regulation and solder level control.
- Optimally adjustable preheating process with top and bottom heating, as well as convection heating in the preheater module.
- Production capacity and investment costs can be flexibly adapted to meet actual needs through this consistent modular design.
- Precise axis system for accurately positioning the individual work-stations.
- Maximum flexibility with quick-change solder nozzles, wettable or non-wettable depending on your application.
- Easy and convenient teaching process, online or offline.
- Unbeatable price/performance ratio.



NXP series selective soldering machine

Micro-dot Drop-jet Fluxer



With a 130-micron orifice controlled by a closed loop servomotor, accurate flux deposition is guaranteed.

Quick Change Nozzles



The nozzle design allows for quicker changeover times. The entire assembly can easily be removed for maintenance or allow for quick removal of the tip for changing to a different size.

- Closed loop servo axis for solder pot and fluxing unit with X-Y platform;
- Heated N2 at the soldering nozzle;
- Automatic wave RPM adjustment;
- Topside hot air preheating in solder pot area to make the thermal compensation;

Board handling System



Unique heavy duty board clamping system ensures stability of PCB during soldering and fluxing.

SMEMA conveyor system ;

NXP series selective soldering machine

Live Process View Camera



Live viewing of the soldering can assist in the process setup and continuous monitoring throughout the process. Both video and still images can be acquired from the software for archiving.

Bottom Side Preheater



Fast reacting quartz IR preheater as standard options ensures precise preheating and flux activation before soldering.

Topside Heaters



Topside convection heaters ensure the best soldering results even on the most challenging assemblies. Top heaters can be installed directly over the bottom preheat for additional preheating and/or directly over the solder pot for continuous process heat.

User friendly programming software



Offline programming software is included and can be used either with Gerber or JPG's, inputting the x and y coordinates. There is no need to interrupt production to make new programs.